

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Ian P. Shaeffer et al.  
Filed: Herewith  
Docket No.: 10002500-2 (H300.146.102)  
Title: A METHOD OF FABRICATING A SUBSTANTIALLY ZERO SIGNAL  
DEGRADATION ELECTRICAL CONNECTION ON A PRINTED  
CIRCUIT BOARD

**Divisional Application of:**

Applicant:	Ian P. Shaeffer et al.	Examiner:	Jeremy C. Norris
Serial No.:	09/561,591	Group Art Unit:	2827
Filed:	May 1, 2000	Docket No.:	10002500-1
Title:	PRINTED CIRCUIT BOARD HAVING SOLDER BRIDGES FOR ELECTRONICALLY CONNECTING CONDUCTING PADS AND METHOD FOR FABRICATING SOLDER BRIDGES		

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Mail Stop Patent Application  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**PRELIMINARY AMENDMENT**

Dear Sir:

This Preliminary Amendment modifies the U.S. Divisional Patent Application filed herewith. Please amend the above-identified application as follows:

**Preliminary Amendment**

Applicant: Ian P. Shaeffer et al.

Filed: Herewith

Docket No.: 10002500-2

Title: PRINTED CIRCUIT BOARD HAVING SOLDER BRIDGES FOR ELECTRONICALLY  
CONNECTING CONDUCTING PADS AND METHOD FOR FABRICATING SOLDER BRIDGES

**Divisional Application of:**

Applicant: Ian P. Shaeffer et al.

Serial No.: 09/561,591

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CONNECTING CONDUCTING PADS AND METHOD FOR FABRICATING SOLDER BRIDGES

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**IN THE TITLE**

Please amend the title of the invention as follows:

~~PRINTED CIRCUIT BOARD HAVING SOLDER BRIDGES FOR ELECTRONICALLY  
CONNECTING CONDUCTING PADS AND METHOD FOR FABRICATING SOLDER  
BRIDGES~~ A METHOD OF FABRICATING A SUBSTANTIALLY ZERO SIGNAL  
DEGRADATION ELECTRICAL CONNECTION ON A PRINTED CIRCUIT BOARD